## Wire Bondable Multi-tap Chip Resistors

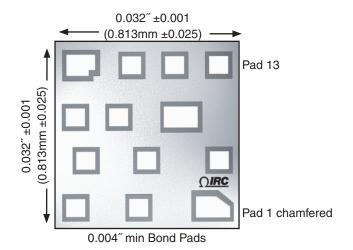


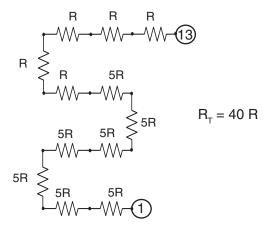
#### **WBC Series**

- · High resistor density
- · MIL inspection available
- · Multi-tapped chip resistor



## Physical Data





#### **Electrical Data**

Absolute Tolerance		to ±5%	
Absolute TCR		to ±25ppm/°C	
Package Power Rating (@ 70°C)		250mW	
Rated Operating Voltage (not to exceed $\sqrt{P \times R}$ )		100V	
Operating Temperature		-55°C to +150°C	
Noise		<-30dB	
Substrate Material		Oxidized Silicon (10KÅ SiO <sub>2</sub> minimum)	
Substrate Thickness		0.010" ±0.001 (0.254mm ±0.025)	
Bond Pad Metallization	Aluminum	10KÅ minimum	
	Gold	15KÅ minimum	
Backside		Silicon (gold available)	
Passivation		Silicon Dioxide or Silicon Nitride	



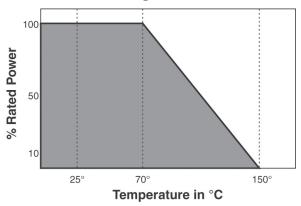




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## **Power Derating Data**



## TCR/Inspection Code Table

Absolute TCR	Commercial Code	MIL Inspection Code*
±300ppm/°C	00	04
±100ppm/°C	01	05
±50ppm/°C	02	06
±25ppm/°C	03	07

<sup>\*</sup>Notes: Product supplied to Class H of MIL-PRF 38534 include 100% visual inspection

#### **Environmental Data**

Test	Method	Max ∆R	Typical ∆R
Thermal Shock	MIL-STD-202 Method 107 Test condition F	±0.1%	±0.02%
High Temperature Exposure	MIL-STD-883 Method 1008 150°C, 1000 hours	±0.1%	±0.05%
Low Temperature Storage	-55°C, 1000 hours	±0.03%	±0.01%
Life	MIL-STD-202 Method 108 70°C, 1000 hours	±0.5%	±0.01%
Life at Elevated Temperature	MIL-STD-202 Method 108 125°C, 1000 hours	±0.5%	±0.05%

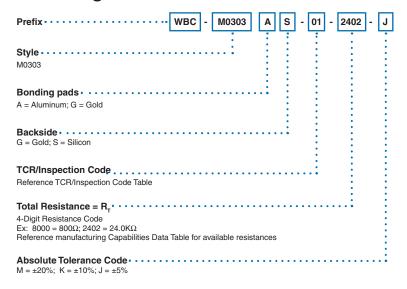
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#### Manufacturing Capabilities Data

Resistance R Total	Available Absolute Tolerances	Best Absolute TCR
100Ω	МК	±100ppm/°C
400Ω	ΜKJ	±100ppm/°C
800Ω	МКЈ	±100ppm/°C
2.4ΚΩ	МКЈ	±50ppm/°C
8.0ΚΩ	МКЈ	±50ppm/°C
24ΚΩ	ΜKJ	±25ppm/°C
80ΚΩ	МКЈ	±25ppm/°C

#### **Ordering Data**



Packaging
Standard packaging is 2" x 2" chip tray. For additional information or to discuss your specific requirements, please contact our Applications Team using the contact details below.